

## WHAT IS CLAIMED IS:

1. A semiconductor integrated circuit device having bumps, which are used for electrically connecting by face down bonding and provided in a terminal section on a surface of a semiconductor substrate thereof, said semiconductor integrated circuit device further comprising:
- 5                   facedown bonding dummy bumps which are connected non-electrically and disposed in a vicinity of one or more corner sections of four corners of a semiconductor chip, wherein an area of each of said facedown bonding dummy bumps projected onto a chip is larger than that of the area of each said facedown bonding bumps.
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